

TOSHIBA

100FXFG13, 100FXFH13

TOSHIBA FAST RECOVERY DIODE SILICON DIFFUSED TYPE

100FXFG13, 100FXFH13

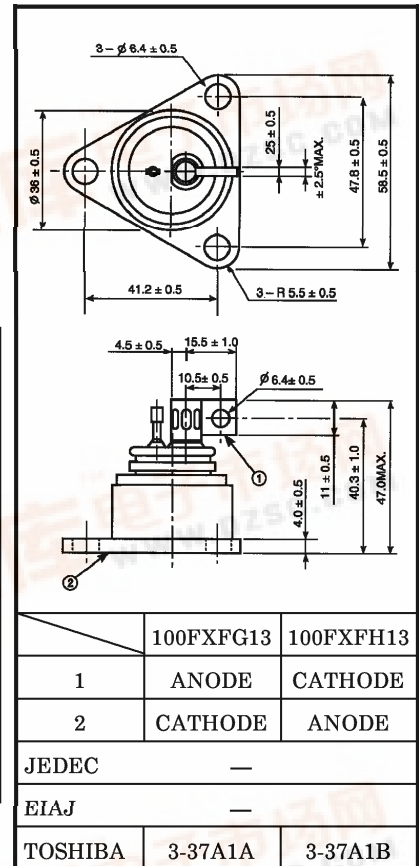
HIGH SPEED RECTIFIER APPLICATIONS

Unit in mm

- Repetitive Peak Reverse Voltage : $V_{RRM}=3300V$
- Average Forward Current : $I_F(AV)=100A$
- Reverse Recovery Time ($T_j=25^\circ C$) : $t_{rr}=3.1\mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	3300	V
Non-Repetitive Peak Reverse Voltage (Non-Repetitive $\leq 5ms$, $T_j=0\sim 125^\circ C$)	V_{RSM}	3400	V
Average Forward Current	$I_F(AV)$	100	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	2000 (50Hz)	A
		2200 (60Hz)	
Junction Temperature Range	T_j	$-40\sim 125$	$^\circ C$
Storage Temperature Range	T_{stg}	$-40\sim 125$	$^\circ C$
Screw Torque	—	1.6	N·m



Weight : 200g

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	MAX.	UNIT	
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM}=3300V, T_j=125^\circ C$	—	30	mA	
Peak Forward Voltage	V_{FM}	$I_{FM}=320A, T_j=25^\circ C$	—	2.2	V	
Reverse Recovery Time	t_{rr}	$I_F=100A$ $di_F/dt=100A/\mu s$	$T_j=25^\circ C$	—	3.1	μs
			$T_j=125^\circ C$	—	4.0	
Thermal Resistance	$R_{th(j-c)}$	Junction to Fin	—	0.18	$^\circ C/W$	

Note : Contact thermal resistance $R_{th(c-f)}=0.04^\circ C/W$ (Applied silicone grease)

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